

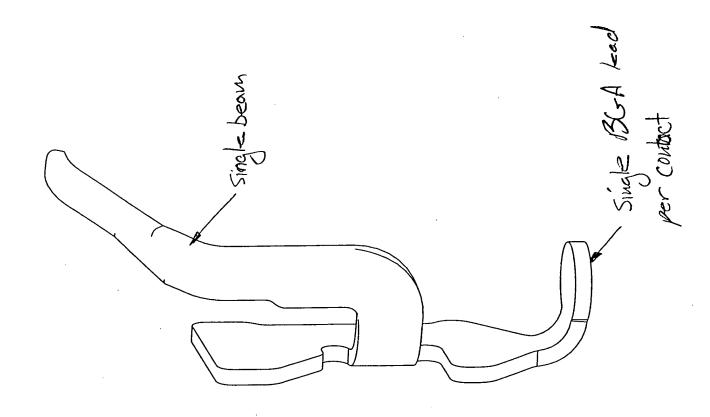
JAN 1 Z 2005 W 1 2 2005 THIS PRODUCT
HAS NOT COMPLETED
VALIDATION/QUALIFICATION
TESTING 1489825 2. CONTACT TIP LOCATION SHOWN PRIOR TO ACTUATION 0.0.0.0.0.0.0.0.0.0.0.0 1. SOCKET VIEWS DEPOPULATED FOR CLARITY 3. EUTECTIC SOLDER BALLS, 635n37Pb 4. MATERIAL: HOUSING: LCP UL94V-0, CONTACT: COPPER ALLOY PRODUCT NUMBER WILL BE ASSIGNED WHEN RELEASED DESIGN IS SUBJECT TO CHANGE WITHOUT NOTICE PROPOSED DESIGN CTF DIMENSION THE REPORT OF THE PARTY OF THE "MANAGEMENTS" 22777 V ⋖ CONFIDENTIAL BEFORE SOLDER
BALL REFLOW ÷ (5.2) SECTION ILLUSTRATES HOUSING IN FINAL SEATING POSITION IN FRAME AFTER NOWINAL SOLDER BALL REFLOW SOLDER BALL SHOWN BEFORE REFLOW 1.27 2.43 ₹3.00 SECTION E-E 3. 2. "Poior act ▲ 0.33 AFTER FRAME ACTUATION TO HOTHERBOARD AFTER REFLOW A # 10.21ABC-44.8±0.2 & 0.10 CONTACT TIP POSITION AFTER DEFLECTION -SEE DETAIL 14.60±0.05 A 8 -SEE DETAIL 8 DETAIL G SCALE 30:1 آ ۾ 10.5 1489825-1 AS SHOWN IN PRE-SEATED POSITION OF CONTACT POINT - 15.00±0.05 - 15.00±0.05 - 15.00±0.05 37.60±0.05 [7.4] o H H - 44.8±0.2 -[ **4** DETAIL F LGA735 0 1.092 4 y t I.379 TO CENTER OF CONTACT POINT 37.25 2 P.C 37.60±0.05

OIPE

contact oriented in

same direction





"Prior Art"